

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|--------|--|---|------------------|---------|---------------------|
| L1 | 145283 | (heat near5 (sink spread\$3 dissipat\$3)) | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 12:31 |
| L2 | 75908 | (substrate wafer) near100 (trench recess groove) | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 11:32 |
| L3 | 186258 | (substrate wafer) near100 (trench hole open\$3 recess groove) | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 12:31 |
| L4 | 12798 | 1 and 3 | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 11:33 |
| L5 | 1545 | 4 and ((coolant (cooling near5 (liquid fluid))) | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 12:32 |
| L7 | 630 | 5 and ((coolant (cooling near5 (liquid fluid))) same (trench hole open\$3 recess groove)) | US-PGPU B; USPAT; USOCR | OR | ON | 2005/10/21 11:35 |
| L8 | 69509 | (heat near5 (sink spread\$3 dissipat\$3)) | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:31 |
| L9 | 167932 | (substrate wafer) near100 (trench hole open\$3 recess groove) | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:31 |
| L10 | 258386 | (substrate wafer)and (trench hole open\$3 recess groove) | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:31 |
| L11 | 258386 | 9 10 | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:32 |
| L12 | 3276 | 11 and 8 | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:32 |

| | | | | | | |
|-----|----|--|---|----|----|---------------------|
| L13 | 85 | 12 and (coolant (cooling near5 (liquid fluid))) | EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/10/21 12:32 |
|-----|----|--|---|----|----|---------------------|